

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
CHUN-CHIA HSU	03/22/2018
CHIEH HSIEH	03/20/2018
SHANG-CHIEH CHIEN	03/20/2018
LI-JUI CHEN	03/20/2018
PO-CHUNG CHENG	03/22/2018
TZUNG-CHI FU	03/21/2018
BO-TSUN LIU	03/22/2018
RECEIVING PARTY DATA	
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING CO., LTD.
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Internal Address:	HSINCHU SCIENCE PARK
City:	HSINCHU
State/Country:	TAIWAN
Postal Code:	300-78
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15905951
CORRESPONDENCE DATA	
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ATTORNEY DOCKET NUMBER:	2017-2143/24061.3653US01
NAME OF SUBMITTER:	YILUN WANG
SIGNATURE:	/Yilun Wang/

PATENT

DATE SIGNED:	04/06/2018
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Total Attachments: 3

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Docket No.: P20172143US00/24061.3653US01
Customer No.: 42717

ASSIGNMENT

WHEREAS, we,

- (1) Chun-Chia Hsu of Hsinchu, Taiwan, Republic of China
- (2) Chieh Hsieh of Hsinchu, Taiwan, Republic of China
- (3) Shang-Chieh Chien of New Taipei City, Taiwan, Republic of China
- (4) Li-Jui Chen of Hsinchu City, Taiwan, Republic of China
- (5) Po-Chung Cheng of Chiayi County, Taiwan, Republic of China
- (6) Tzung-Chi Fu of Miaoli County, Taiwan, Republic of China
- (7) Bo-Tsun Liu of Taipei City, Taiwan, Republic of China

have invented certain improvements in

SYSTEM AND METHOD FOR EXTREME UNTRAVIOLET SOURCE CONTROL

for which we have executed an application for Letters Patent of the United States of America,

_____ of even date filed herewith; and
X filed on 02-27-2018 and assigned application number 15/905,951; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Co., Ltd., ("TSMC"), 8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, Republic of China is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Chun-Chia Hsu

Residence Address: 8, Li-Hsin Rd. 6, Hsinchu Science Park
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Dated: 2018 3/22
~~Chun-Chia Hsu~~

Chun - Chia Hsu
Inventor Signature

Inventor Name: Chieh Hsieh

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Dated: 2018/3/20

Chieh Hsieh
Inventor Signature

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Dated: 2018/3/20

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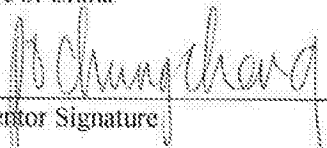
Dated: 2018/3/20

Li-Jui Chen
Inventor Signature

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Dated: 2018 3/22


Inventor Signature

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Dated: Tzung-chi Fu
2018 3/22


Inventor Signature

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Dated: 2018 3/22


Inventor Signature